IN THE CLAIMS

Please cancel claims 1-3, 11-13, 23 and 24 without prejudice or disclaimer of their subject matter, amend claims 4, 5, 9, 14, 15, 19, 21, 25 and 26 as follows:

Claims 1-3. (Canceled)

2

5

1

2

1

2

1

2

- 4. (Currently Amended) [[The]] A thin film transistor of claim 3, comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer;
- wherein one of the source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the titanium and the aluminum-based layers;
- wherein the diffusion prevention layer is a titanium nitride layer; and
 wherein the titanium nitride layer contains 5 to 85 wt% of nitrogen.
 - 5. (Currently Amended) The thin film transistor of claim [[3]] 4, wherein the titanium nitride layer has a thickness of about 100 to 600Å.
 - 6. (Original) The thin film transistor of claim 5, wherein the titanium nitride layer has a thickness of about 100 to 400Å.
 - 7. (Original) The thin film transistor of claim 6, wherein the titanium nitride layer has a thickness of 200 to 400Å.

- 8. (Original) The thin film transistor of claim 7, wherein the titanium nitride layer has a thickness of about 300Å.
- 9. (Currently Amended) [[The]] A thin film transistor of claim 1, comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer, wherein one of the source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the titanium and the aluminum-based layers, and wherein the aluminum-based metal layer is made of an aluminum alloy containing about 0.5 to 5 wt% of one element being selected from the group consisting of silicon, copper, neodymium, platinum, and nickel.
- 10. (Original) The thin film transistor of claim 9, wherein the aluminum-based metal layer is made of an aluminum-silicon alloy containing about 2 wt% of silicon.

Claims 11-13. (Canceled)

ı

- 14. (Original) [[The]] A flat panel display of claim 13, comprising a plurality of sub-pixels driven by thin film transistors, each of the thin film transistors comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer;
- wherein at least one of the source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the aluminum-based metal layer and the titanium layer;
 - wherein the diffusion prevention layer is a titanium nitride layer; and

wherein the titanium nitride layer contains 5 to 85 wt% of nitrogen.

8

1

2

2

1

2

1

2

3

5

7

9

- 1 15. (Currently Amended) The flat panel display of claim [[13]] 14, wherein the titanium nitride layer has a thickness of about 100 to 600Å.
 - 16. (Original) The flat panel display of claim 15, wherein the titanium nitride layer has a thickness of about 100 to 400Å.
 - 17. (Original) The flat panel display of claim 16, wherein the titanium nitride layer has a thickness of 200 to 400Å.
 - 18. (Original) The flat panel display of claim 17, wherein the titanium nitride layer has a thickness of about 300Å.
 - 19. (Currently Amended) [[The]] A flat panel display of claim 11, comprising a plurality of sub-pixels driven by thin film transistors, each of the thin film transistors comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer, wherein at least one of the source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the aluminum-based metal layer and the titanium layer, and wherein the aluminum-based metal layer is made of an aluminum alloy containing about 0.5 to 5 wt% of one element being selected from the group consisting of silicon, copper, neodymium, platinum, and nickel.

1	20. (Original) The flat panel display of claim 19, wherein the aluminum-based metal
2	layer is made of an aluminum-silicon alloy containing about 2 wt% of silicon.
.1	21. (Currently Amended) A flat panel display, comprising:
2	driving circuits disposed along edges of said display;
3	a plurality of sub-pixels driven by thin film transistors; and
4	conductive lines connecting the driving circuits disposed along edges of said display
5	to each of said plurality of sub-pixels, wherein said conductive lines comprise an
6	aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed
7	between the aluminum-based metal layer and the titanium layer:
8	wherein the diffusion prevention layer is a titanium nitride layer; and
9	wherein said titanium nitride layer is 300 Å thick.
10	22. (Original) The flat panel display of claim 21, wherein the diffusion prevention
11	layer and the titanium layer are orderly formed on opposite sides of the aluminum-based

Claims 23-24. (Canceled)

metal layer.

12

1

25. (Currently Amended) The display of claim [[24]] 22, said conductive lines being subjected to a heat treatment of 380°C.

1	26. (Currently Amended) A process for making a flat panel display, comprising:
2	disposing driving circuits along edges of said display;
3	arranging a plurality of sub-pixels driven by thin film transistors; and
• 4	operatively connecting electrically conductive lines between the driving circuits
5	disposed along edges of said display and each of said plurality of sub-pixels, wherein said
6	conductive lines comprise an aluminum-based metal layer, a titanium layer, and a diffusion
7	prevention layer interposed between the aluminum-based metal layer and the titanium layer;
8	wherein the titanium nitride layer contains 5 to 85 wt% of nitrogen.

27. (Previously Presented) The process of claim 26, comprised of orderly forming the diffusion prevention layer and the titanium layer on opposite sides of the aluminum-based metal layer.

2

2

28. (Previously Presented) The process of claim 26, wherein the diffusion prevention layer is a titanium nitride layer.